TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (Ultra High speed U-MOSIII)

TENTATIVE

TPCA8014-H

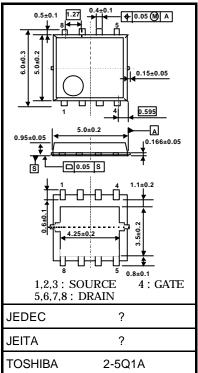
High Speed and High Efficiency DC-DC Converters Notebook PC Applications Portable Equipment Applications

- Small footprint due to small and thin package
- High speed switching
- Small gate charge: Qsw = 7.4 nC (typ.)
- Low drain-source ON resistance: RDS (ON) = 10.5 mO (typ.)
- High forward transfer admittance: $|Y_{fs}| = TBD S$ (typ.)
- Low leakage current: $IDSS = 10 \mu A \text{ (max) (V}DS = 40 \text{ V)}$
- Enhancement mode: $V_{th} = 1.1 \text{ to } 2.3 \text{ V } (V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA})$

Maximum Ratings (Ta = 25°C)

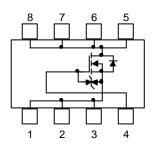
Characte	ristics	Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	40	V	
Drain-gate voltage (F	$R_{GS} = 20 \text{ k}\Omega$	V_{DGR}	40	V	
Gate-source voltage		V_{GSS}	±20	V	
Drain current	DC (Note 1)	l _D	30	Α	
Diam curient	Pulsed (Note 1)	l _{DP}	90	^	
Drain power dissipat	ion (Tc=25)	P_{D}	45	W	
Drain power dissipation	on $(t = 10 s)$ (Note 2a)	P_{D}	2.8	W	
Drain power dissipation	on $(t = 10 s)$ (Note 2b)	P_{D}	1.6	W	
Single pulse avalanch	ne energy (Note 3)	E _{AS}	84	mJ	
Avalanche current		I _{AR}	30	Α	
Repetitive avalanche	energy c=25) (Note 4)	E _{AR}	TBD	mJ	
Channel temperature	Channel temperature		150	°C	
Storage temperature	range	T _{stg}	-55 to 150	°C	

Unit: mm



Weight: 0.080 g (typ.)

Circuit Configuration



Note: For (Note 1), (Note 2), (Note 3), (Note 4), please refer to the next page.

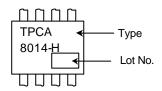
This transistor is an electrostatic sensitive device. Please handle with caution.



Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case (Tc=25)	R _{th (ch-c)}	2.78	°C/W
Thermal resistance, channel to ambient $(t = 10 \text{ s})$ (Note 2a)	R _{th (ch-a)}	44.6	°C/W
Thermal resistance, channel to ambient $(t = 10 \text{ s})$ (Note 2b)	R _{th (ch-a)}	78.1	°C/W

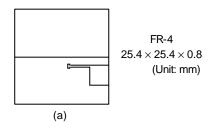
Marking (Note 5)

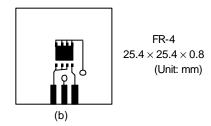


Note 1: Please use devices on condition that the channel temperature is below 150 °C.

Note 2: (a) Device mounted on a glass-epoxy board (a)

(b) Device mounted on a glass-epoxy board (b)

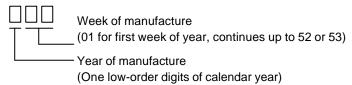




Note 3: $V_{DD} = 24 \text{ V}$, $T_{ch} = 25 ^{\circ}\text{C}$ (initial), L = 0.1 mH, $R_G = 25 \Omega$, $I_{AR} = 30 \text{ A}$

Note 4: Repetitive rating: pulse width limited by max channel temperature

Note 5: * Weekly code: (Three digits)





Electrical Characteristics (Ta = 25°C)

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	rrent	l _{GSS}	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μΑ
Drain cut-OFF cu	urrent	I _{DSS}	$V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}$	_	_	10	μΑ
Drain source bro	akdown voltago	V (BR) DSS	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	40		V	
Drain-source breakdown voltage		V (BR) DSX	$I_D = 10 \text{ mA}, V_{GS} = -20 \text{ V}$	25		_	v
Gate threshold v	oltage	V_{th}	$V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA}$	1.1	_	2.3	V
Drain-source ON	resistance	Pro (OLI)	$V_{GS} = 10 \text{ V}, I_D = 15 \text{ A}$	_	7.0	9.5	mΩ
Dialii-30dice Oiv	resistance	NDS (ON)	$V_{GS} = 4.5 V$, $I_D = 15 A$		10.5	15	
Forward transfer	admittance	Y _{fs}	$V_{DS} = 10 \text{ V}, I_D = 15 \text{ A}$	TBD	TBD	_	S
Input capacitanc	e	C _{iss}			1365		
Reverse transfer capacitance		C _{rss}	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		110		pF
Output capacitance		Coss			500	_	
Gate resistance	te resistance				1.0	_	
	Rise time	t _r	10 V □ h = 15 A	_	5		
Drain-source breakdown voltage V (BR) DSS I _D = 10 mA, V _{GS} = 0 V 40 — V (BR) DSX I _D = 10 mA, V _{GS} = -20 V 25 — Gate threshold voltage V _{th} V _{DS} = 10 V, I _D = 1 mA 1.1 — Drain-source ON resistance R _{DS} (ON) V _{GS} = 10 V, I _D = 15 A — 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7.0 7		20					
Switching time	ward transfer admittance $ Y_{fs} $ $ V_{DS} = 15 \text{A}$ $ V_{DS} = 10 \text{V}$,	_	ns				
	Turn-OFF time	t _{off}		_	18	_	
Total gate charge	ge V _{DD} ≈ 32 V, V _{GS} = 10 V, I _D = 30 A —		22	_			
(gate-source plus	s gate-drain)	∠ g	$V_{DD} \simeq 32 \text{ V}, V_{GS} = 5 \text{ V}, I_D = 30 \text{ A}$		_ 12 _		
Gate-source charge 1		Q _{gs1}	$V_{DD} \simeq 32 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 30 \text{ A}$		5.1		nC
Gate-drain ("miller") charge		Q_{gd}			4.9	_	
. , ,		Q_{SW}]	_	7.4	_	

Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteri	Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse	(Note 1)	I _{DRP}	_	_	_	90	Α
Forward voltage (diode)			V_{DSF}	$I_{DR} = 30 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	-1.2	V

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